| Electronic Acknowledgement Receipt | | | | |
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| EFS ID: | 3426343 | | | |
| Application Number: | 10612222 | | | |
| International Application Number: | | | | |
| Confirmation Number: | 5751 | | | |
| Title of Invention: | Component-embedded board fabrication method and apparatus for high-precision and easy fabrication of component-embedded board with electronic components embedded in wiring board | | | |
| First Named Inventor/Applicant Name: | Masatoshi Akagawa | | | |
| Customer Number: | 21171 | | | |
| Filer: | Aaron Colby Walker/Gabriel Kabik | | | |
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| Application Type: | Utility under 35 USC 111(a) | | | |
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Payment information:

| Submitted with Payment | no |
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File Listing:

| 1 Information Disclosure Statement Letter IDSLetter.pdf 151231 no 4 | Document Number | Document Description | File Name | File Size(Bytes) /Message Digest | Multi Part /.zip | Pages (if appl.) |
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| | 1 | | IDSLetter.pdf | 12de682ed8d16515ad58cfb8da8f22c71 | no | 4 |

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| 2 Information Disclosure Statement (IDS) Filed | | Form1449.pdf | 157267 | no | 3 | |
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| | i omir rie.pai | b12cf5bfbd7abdc51411f2ed622d9ee53 a892963 | 110 | | | |
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| O NEL Descriptor | IDOA ndf | 131900 | no | 4 | | |
| 3 NPL Documents | JPOA.pdf | 25031b7e3f7ca13a968b028249f0af314 2a8d9b3 | no | 4 | | |
| Warnings: | | | | | | |
| Information | Information: | | | | | |
| 4 Foreign Reference | Ref1.pdf | 469367 | no | 8 | | |
| 4 Totalgit Neterence | rieir.pui | 19d2158c50fa318384bd05c811ba44b0 22f67460 | 110 | | | |
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If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

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